ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES INDUSTRIES International and Pan-Am	Bannockburn, Illino	is. All rights reserved	under both	This docume level parts, t	ent is a declara he declaration	ion of the su	ibstances s all lower	within the manufactur level materials for w	rer listed it hich the m	tem. Note: if nanufacturer	f the item is an as has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Information												
Company name*	y unique ID	que ID U			Unique ID Authority				Response Date*			
nsemi									2023-06-08			
ntact Name Title - Contact					Phone - Contact*				Email - Contact*			
roduct-Env-Stewards Product Enviro Complia			mpliance r		NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compl			Compliance		NA			Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number	Mfr Item Name			Effective Date	e Version	N	Manufacturing Site		Weight*	UOM	Unit Type
	NLV14094BDG	4094BDG 8-BIT SHIFT/STO		ł	2023-06-08 PH1		'H1	1	142.68	mg	Each	
Manufacturing Proccess Information		·										·
Terminal Plating / Grid Array Materia	minal Plating / Grid Array Material Terminal Base Alloy		J-STD-020 MSL	Rating	Peak Pro	cess Body To	emperatur	e Max Time at Peak	Temperat	ure Numb	er of Reflow Cyd	les
Matte Tin (Sn) - annealed CU Alloy		1		260		С	30	secon	ds 3			
Comments												
level 1 - maximum time at peak temperature d	uring soldering is	10-30 seconds										
For more information regarding material com	position please ref	er to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIP), Dibusyl phthalate (DIP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

select a ROHS exemption, if appli sigma range of distribution unless	otherwise noted).	it of the substance of the Pl	PM concentration	[F] Optionally enter the positive (+) and n	legative (-) tolerance in per	cent (Note: percer	it tolerance values are	expected to cover a 3
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.73	mg	Supplier	Silicon (Si)	7440-21-3		2.73	mg
Die Attach	4.85	mg	Supplier	Silver (Ag)	7440-22-4		3.6375	mg
			Supplier	Epoxy resins	129915-35-1		1.2125	mg
Lead Frame	75.92	mg	Supplier	Silver (Ag)	7440-22-4		0.7592	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1518	mg
			Supplier	Iron (Fe)	7439-89-6		1.9739	mg
			Supplier	Copper (Cu)	7440-50-8		73.035	mg
Mold Compound-Black	55.11	mg		Epoxy resin	proprietary data		2.7555	mg
			Supplier	Phenolic Resin	Proprietary Data		2.7555	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.1022	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2756	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.2213	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	0.34	mg	Supplier	Copper (Cu)	7440-50-8		0.34	mg